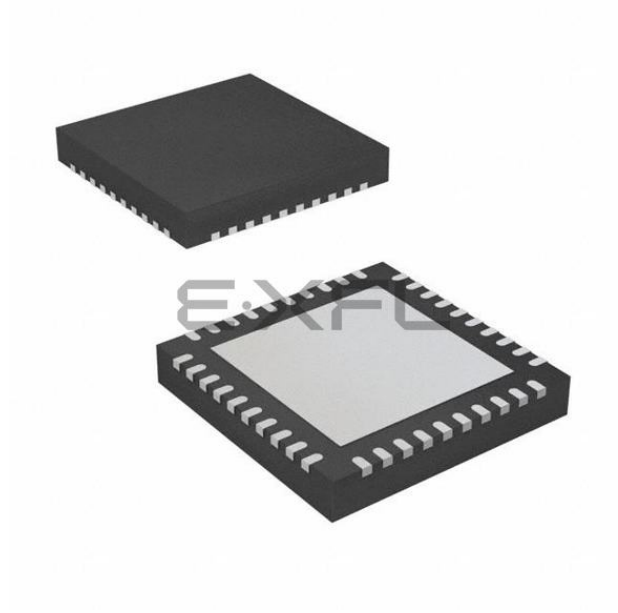

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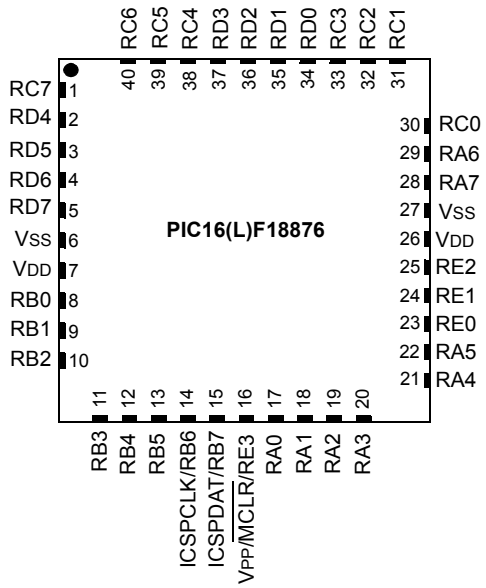
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	36
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 35x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf18876-e-mv

40-pin UQFN (5x5)

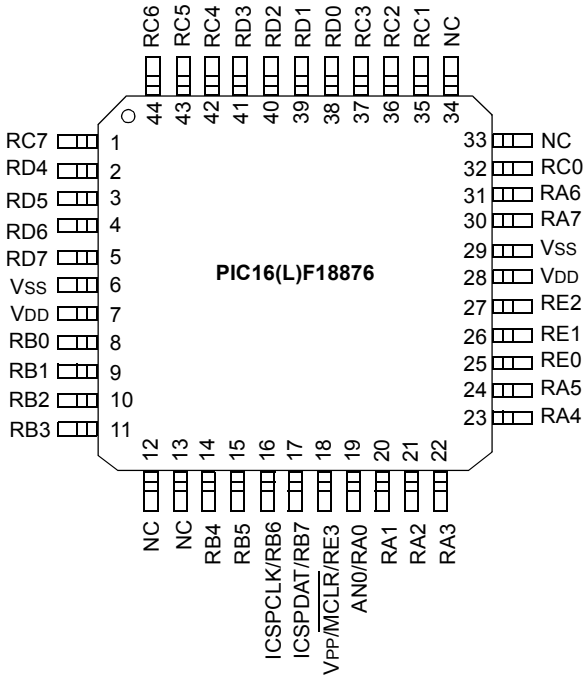


Note 1: See Table 3 for location of all peripheral functions.

2: All VDD and all VSS pins must be connected at the circuit board level. Allowing one or more VSS or VDD pins to float may result in degraded electrical performance or non-functionality.

3: The bottom pad of the QFN/UQFN package should be connected to VSS at the circuit board level.

44-pin TQFP (10x10)



Note 1: See Table 3 for location of all peripheral functions.

2: All VDD and all VSS pins must be connected at the circuit board level. Allowing one or more VSS or VDD pins to float may result in degraded electrical performance or non-functionality.

REGISTER 4-3: CONFIG3: CONFIGURATION WORD 3: WINDOWED WATCHDOG

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
WDTCCS<2:0>			WDTCWS<2:0>		
bit 13					bit 8

U-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
	WDTE<1:0>		WDTCPS<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	x = Bit is unknown	U = Unimplemented bit, read as ‘1’
‘0’ = Bit is cleared	‘1’ = Bit is set	W = Writable bit	n = Value when blank or after Bulk Erase

bit 13-11 **WDTCCS<2:0>**: WDT Input Clock Selector bits
- 111 = Software Control
- 110 = Reserved
- .
- .
- .
- 010 = Reserved
- 001 = WDT reference clock is the MFINTOSC/16 output (31.25 kHz)
- 000 = WDT reference clock is the 31.0 kHz LFINTOSC (default value)

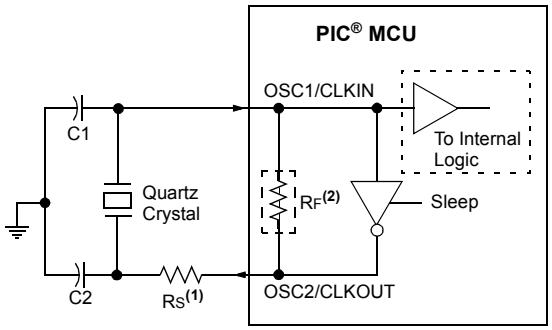
bit 10-8 **WDTCWS<2:0>**: WDT Window Select bits

WDTCWS	WDTWS at POR			Software control of WDTWS?	Keyed access required?
	Value	Window delay Percent of time	Window opening Percent of time		
111	111	n/a	100	Yes	No
110	111	n/a	100	No	Yes
101	101	25	75		
100	100	37.5	62.5		
011	011	50	50		
010	010	62.5	37.5		
001	001	75	25		
000	000	87.5	12.5		

bit 7 **Unimplemented**: Read as ‘1’

bit 6-5 **WDTE<1:0>**: WDT Operating mode:
- 11 = WDT enabled regardless of Sleep; SWDTEN is ignored
- 10 = WDT enabled while Sleep = 0, suspended when Sleep = 1; SWDTEN ignored
- 01 = WDT enabled/disabled by SWDTEN bit in WDTCON0
- 00 = WDT disabled, SWDTEN is ignored

FIGURE 6-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

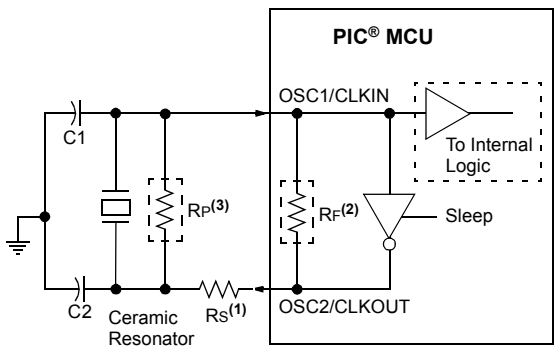
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Application Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 6-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

6.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR), or a wake-up from Sleep. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

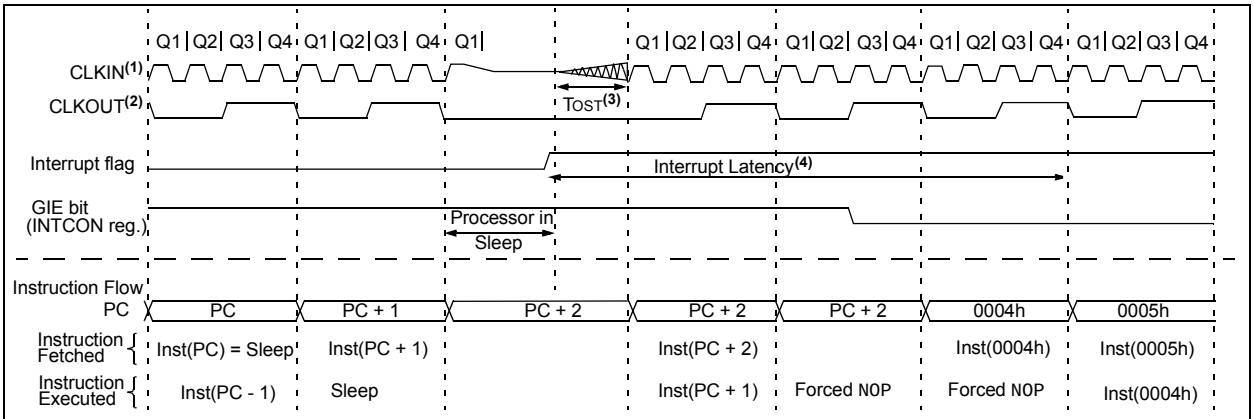
8.2.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source, with the exception of the clock switch interrupt, has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction
  - SLEEP instruction will execute as a NOP
  - WDT and WDT prescaler will not be cleared
  - $\overline{TO}$ bit of the STATUS register will not be set
  - $\overline{PD}$ bit of the STATUS register will not be cleared
- If the interrupt occurs **during or after** the execution of a SLEEP instruction
  - SLEEP instruction will be completely executed
  - Device will immediately wake-up from Sleep
  - WDT and WDT prescaler will be cleared
  - $\overline{TO}$ bit of the STATUS register will be set
  - $\overline{PD}$ bit of the STATUS register will be cleared

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

FIGURE 8-2: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: External clock. High, Medium, Low mode assumed.
2: CLKOUT is shown here for timing reference.
3: TOST = 1024 TOSC. This delay does not apply to EC and INTOSC Oscillator modes.
4: GIE = 1 assumed. In this case after wake-up, the processor calls the ISR at 0004h. If GIE = 0, execution will continue in-line.

8.2.3 LOW-POWER SLEEP MODE

The PIC16F18855/75 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode.

The PIC16F18855/75 allows the user to optimize the operating current in Sleep, depending on the application requirements.

Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. Depending on the configuration of these bits, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

8.2.3.1 Sleep Current vs. Wake-up Time

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking-up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The Normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

REGISTER 12-38: SLRCOND: PORTD SLEW RATE CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
SLRD7	SLRD6	SLRD5	SLRD4	SLRD3	SLRD2	SLRD1	SLRD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SLRD<7:0>:** PORTD Slew Rate Enable bits
For RD<7:0> pins, respectively
1 = Port pin slew rate is limited
0 = Port pin slews at maximum rate

REGISTER 12-39: INLVLD: PORTD INPUT LEVEL CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
INLVLD7	INLVLD6	INLVLD5	INLVLD4	INLVLD3	INLVLD2	INLVLD1	INLVLD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **INLVLD<7:0>:** PORTD Input Level Select bits
For RD<7:0> pins, respectively
1 = ST input used for PORT reads and interrupt-on-change
0 = TTL input used for PORT reads and interrupt-on-change

REGISTER 15-4: IOCBP: INTERRUPT-ON-CHANGE PORTB POSITIVE EDGE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **IOCBP<7:0>:** Interrupt-on-Change PORTB Positive Edge Enable bits
1 = Interrupt-on-Change enabled on the pin for a positive-going edge. IOCBFx bit and IOCIF flag will be set upon detecting an edge.
0 = Interrupt-on-Change disabled for the associated pin.

REGISTER 15-5: IOCBN: INTERRUPT-ON-CHANGE PORTB NEGATIVE EDGE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **IOCBN<7:0>:** Interrupt-on-Change PORTB Negative Edge Enable bits
1 = Interrupt-on-Change enabled on the pin for a negative-going edge. IOCBFx bit and IOCIF flag will be set upon detecting an edge.
0 = Interrupt-on-Change disabled for the associated pin.

REGISTER 15-6: IOCBF: INTERRUPT-ON-CHANGE PORTB FLAG REGISTER

R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0
IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HS - Bit is set in hardware

bit 7-0 **IOCBF<7:0>:** Interrupt-on-Change PORTB Flag bits
1 = An enabled change was detected on the associated pin.
Set when IOCBPx = 1 and a rising edge was detected on RBx, or when IOCBNx = 1 and a falling edge was detected on RBx.
0 = No change was detected, or the user cleared the detected change.

20.5 Dead-Band Control

The dead-band control provides non-overlapping PWM signals to prevent shoot-through current in PWM switches. Dead-band operation is employed for Half-Bridge and Full-Bridge modes. The CWG contains two 6-bit dead-band counters. One is used for the rising edge of the input source control in Half-Bridge mode or for reverse dead-band Full-Bridge mode. The other is used for the falling edge of the input source control in Half-Bridge mode or for forward dead band in Full-Bridge mode.

Dead band is timed by counting CWG clock periods from zero up to the value in the rising or falling dead-band counter registers. See CWGxDBR and CWGxDBF registers, respectively.

20.5.1 DEAD-BAND FUNCTIONALITY IN HALF-BRIDGE MODE

In Half-Bridge mode, the dead-band counters dictate the delay between the falling edge of the normal output and the rising edge of the inverted output. This can be seen in Figure 20-9.

20.5.2 DEAD-BAND FUNCTIONALITY IN FULL-BRIDGE MODE

In Full-Bridge mode, the dead-band counters are used when undergoing a direction change. The MODE<0> bit of the CWGxCON0 register can be set or cleared while the CWG is running, allowing for changes from Forward to Reverse mode. The CWGxA and CWGxC signals will change immediately upon the first rising input edge following a direction change, but the modulated signals (CWGxB or CWGxD, depending on the direction of the change) will experience a delay dictated by the dead-band counters. This is demonstrated in Figure 20-3.

20.6 Rising Edge and Reverse Dead Band

CWGxDBR controls the rising edge dead-band time at the leading edge of CWGxA (Half-Bridge mode) or the leading edge of CWGxB (Full-Bridge mode). The CWGxDBR value is double-buffered. When EN = 0, the CWGxDBR register is loaded immediately when CWGxDBR is written. When EN = 1, then software must set the LD bit of the CWGxCON0 register, and the buffer will be loaded at the next falling edge of the CWG input signal. If the input source signal is not present for enough time for the count to be completed, no output will be seen on the respective output.

20.7 Falling Edge and Forward Dead Band

CWGxDBF controls the dead-band time at the leading edge of CWGxB (Half-Bridge mode) or the leading edge of CWGxD (Full-Bridge mode). The CWGxDBF value is double-buffered. When EN = 0, the CWGxDBF register is loaded immediately when CWGxDBF is written. When EN = 1 then software must set the LD bit of the CWGxCON0 register, and the buffer will be loaded at the next falling edge of the CWG input signal. If the input source signal is not present for enough time for the count to be completed, no output will be seen on the respective output.

Refer to Figure 20.6 and Figure 20-7 for examples.

EQUATION 21-2: R-C CALCULATIONS

V_{PEAK} = External voltage source peak voltage
f = External voltage source frequency
C = Series capacitor
R = Series resistor
V_C = Peak capacitor voltage
Φ = Capacitor induced zero crossing phase advance in radians
T_Φ = Time ZC event occurs before actual zero crossing

$$Z = \frac{V_{PEAK}}{3 \times 10^{-4}}$$

$$X_C = \frac{1}{2\pi fC}$$

$$R = \sqrt{Z^2 - X_C^2}$$

$$V_C = X_C(3 \times 10^{-4})$$

$$\Phi = \mathrm{Tan}^{-1}\left(\frac{X_C}{R}\right)$$

$$T\Phi = \frac{\Phi}{2\pi f}$$

EXAMPLE 21-1: R-C CALCULATIONS

V_{RMS} = 120
$V_{PEAK} = V_{RMS} * \sqrt{2} = 169.7$
f = 60 Hz
C = 0.1 µF

$$Z = \frac{V_{PEAK}}{3 \times 10^{-4}} = \frac{169.7}{3 \times 10^{-4}} = 565.7\text{k}\Omega$$

$$X_C = \frac{1}{2\pi fC} = \frac{1}{(2\pi \times 60 \times 1 \times 10^{-7})} = 26.53\text{k}\Omega$$

$$R = \sqrt{(Z^2 \times X_C^2)} = 565.1\text{k}\Omega \text{ (computed)}$$

$$R = 560\text{k}\Omega \text{ (used)}$$

$$Z_R = \sqrt{R^2 + X_C^2} = 560.6\text{k}\Omega \text{ (using actual resistor)}$$

$$I_{PEAK} = \frac{V_{PEAK}}{Z_R} = 302.7 \times 10^{-6}$$

$$V_C = X_C \times \mathrm{Ipeak} = 8.0\text{V}$$

$$\Phi = \mathrm{Tan}^{-1}\left(\frac{X_C}{R}\right) = 0.047 \text{ radians}$$

$$T\Phi = \frac{\Phi}{2\pi f} = 125.6\mu\text{s}$$

21.5.2 CORRECTION BY OFFSET CURRENT

When the waveform is varying relative to VSS, then the zero cross is detected too early as the waveform falls and too late as the waveform rises. When the waveform is varying relative to VDD, then the zero cross is detected too late as the waveform rises and too early as the waveform falls. The actual offset time can be determined for sinusoidal waveforms with the corresponding equations shown in Equation 21-3.

EQUATION 21-3: ZCD EVENT OFFSET

When External Voltage Source is relative to Vss:

$$T_{OFFSET} = \frac{\mathrm{asin}\left(\frac{Vcpinv}{V_{PEAK}}\right)}{2\pi \bullet Freq}$$

When External Voltage Source is relative to VDD:

$$T_{OFFSET} = \frac{\mathrm{asin}\left(\frac{V_{DD} - Vcpinv}{V_{PEAK}}\right)}{2\pi \bullet Freq}$$

This offset time can be compensated for by adding a pull-up or pull-down biasing resistor to the ZCD pin. A pull-up resistor is used when the external voltage source is varying relative to VSS. A pull-down resistor is used when the voltage is varying relative to VDD. The resistor adds a bias to the ZCD pin so that the target external voltage source must go to zero to pull the pin voltage to the VCPINV switching voltage. The pull-up or pull-down value can be determined with the equations shown in Equation 21-4.

EQUATION 21-4: ZCD PULL-UP/DOWN

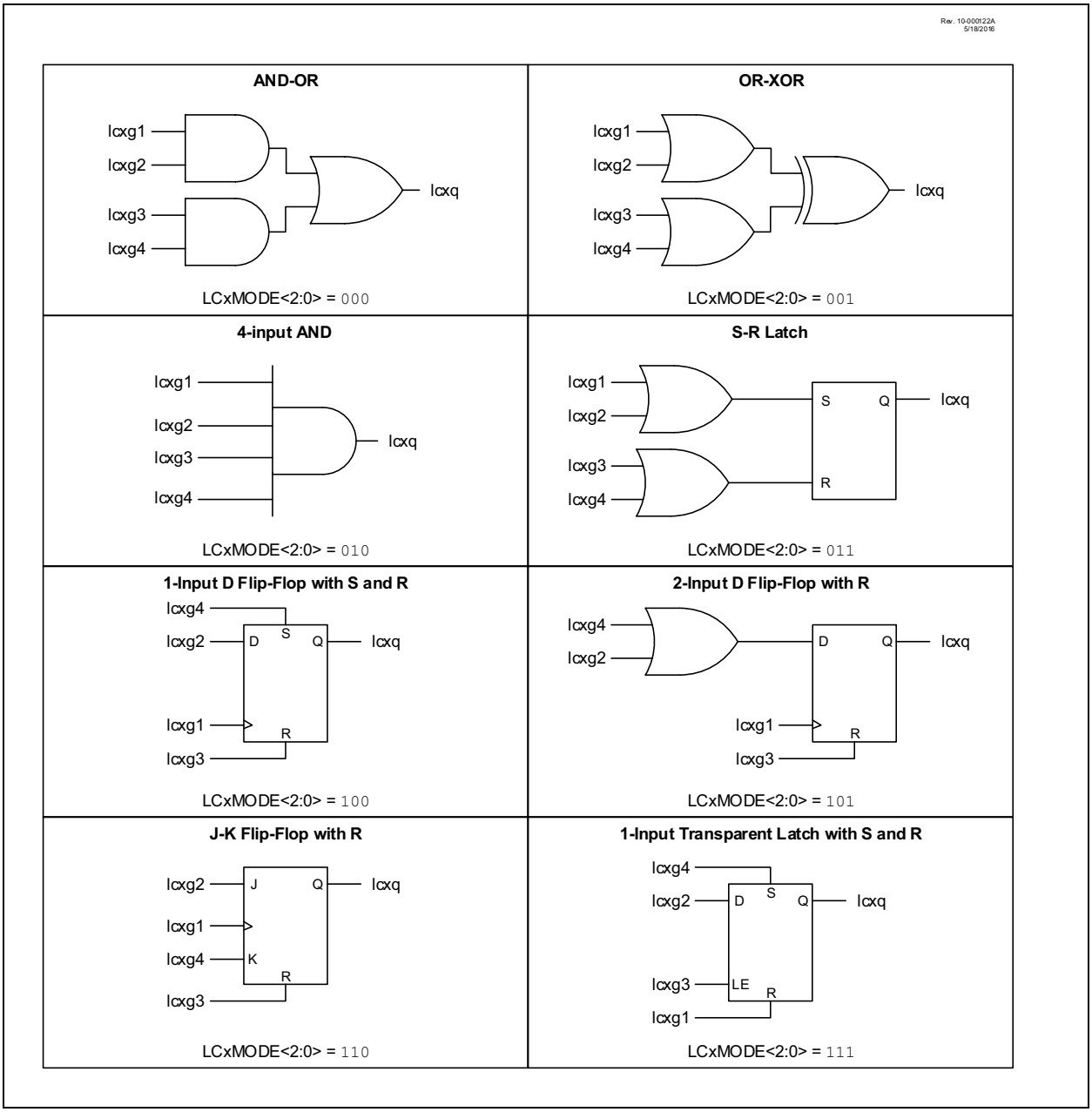
When External Signal is relative to Vss:

$$R_{PULLUP} = \frac{R_{SERIES}(V_{PULLUP} - Vcpinv)}{Vcpinv}$$

When External Signal is relative to VDD:

$$R_{PULLDOWN} = \frac{R_{SERIES}(Vcpinv)}{(V_{DD} - Vcpinv)}$$

FIGURE 22-3: PROGRAMMABLE LOGIC FUNCTIONS



REGISTER 22-3: CLCxSEL0: GENERIC CLCx DATA 0 SELECT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	LCxD1S<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **LCxD1S<5:0>:** CLCx Data1 Input Selection bits
See Table 22-2.

REGISTER 22-4: CLCxSEL1: GENERIC CLCx DATA 1 SELECT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	LCxD2S<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **LCxD2S<5:0>:** CLCx Data 2 Input Selection bits
See Table 22-2.

REGISTER 22-5: CLCxSEL2: GENERIC CLCx DATA 2 SELECT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	LCxD3S<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **LCxD3S<5:0>:** CLCx Data 3 Input Selection bits
See Table 22-2.

REGISTER 22-6: CLCxSEL3: GENERIC CLCx DATA 3 SELECT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	LCxD4S<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **LCxD4S<5:0>:** CLCx Data 4 Input Selection bits
See Table 22-2.

23.2.7 ADC CONVERSION PROCEDURE (BASIC MODE)

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (Refer to the TRISx register)
   - Configure pin as analog (Refer to the ANSELx register)
2. Configure the ADC module:
   - Select ADC conversion clock
   - Configure voltage reference
   - Select ADC input channel (precharge+acquisition)
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt (PEIE bit)
   - Enable global interrupt (GIE bit)**(1)**
4. If ADACQ=0, software must wait the required acquisition time **(2)**.
5. Start conversion by setting the ADGO bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the ADGO bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to **Section 23.3 "ADC Acquisition Requirements"**.

EXAMPLE 23-1: ADC CONVERSION

```
;This code block configures the ADC
;for polling, VDD and VSS references, FRC
;oscillator and AN0 input.
;
;Conversion start & polling for completion
;are included.
;
BANKSEL   ADCON1       ;
MOVLW     B'11110000'  ;Right justify,
FRC
                       ;oscillator
MOVWF     ADCON1       ;Vdd and Vss Vref
BANKSEL   TRISA        ;
BSF       TRISA,0      ;Set RA0 to input
BANKSEL   ANSEL        ;
BSF       ANSEL,0      ;Set RA0 to analog
BANKSEL   ADCON0       ;
MOVLW     B'00000001'  ;Select channel AN0
MOVWF     ADCON0       ;Turn ADC On
CALL      SampleTime   ;Acquisiton delay
BSF       ADCON0,ADGO  ;Start conversion
BTFSC     ADCON0,ADGO  ;Is conversion done?
GOTO      $-1          ;No, test again
BANKSEL   ADRESH       ;
MOVF      ADRESH,W     ;Read upper 2 bits
MOVWF     RESULTHI     ;store in GPR space
BANKSEL   ADRESL       ;
MOVF      ADRESL,W     ;Read lower 8 bits
```

REGISTER 23-5: ADSTAT: ADC THRESHOLD REGISTER

R-0/0	R-0/0	R-0/0	R/C/HS-0/0	U-0	R-0/0	R-0/0	R-0/0
ADAOV	ADUTHR	ADLTHR	ADMATH	—	ADSTAT<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ADAOV:** ADC Computation Overflow bit
1 = ADC accumulator or ADERR calculation have overflowed
0 = ADC accumulator and ADERR calculation have not overflowed

bit 6 **ADUTHR:** ADC Module Greater-than Upper Threshold Flag bit
1 = ADERR >ADUTH
0 = ADERR≤ADUTH

bit 5 **ADLTHR:** ADC Module Less-than Lower Threshold Flag bit
1 = ADERR<ADLTH
0 = ADERR≥ADLTH

bit 4 **ADMATH:** ADC Module Computation Status bit
1 = Registers ADACC, ADFLTR, ADUTH, ADLTH and the ADAOV bit are updating or have already updated
0 = Associated registers/bits have not changed since this bit was last cleared

bit 3 **Unimplemented**: Read as '0'

bit 2-0 **ADSTAT<0:2>:** ADC Module Cycle Multistage Status bits(1)
111 = ADC module is in 2nd conversion stage
110 = ADC module is in 2nd acquisition stage
101 = ADC module is in 2nd precharge stage
100 = Not used
011 = ADC module is in 1st conversion stage
010 = ADC module is in 1st acquisition stage
001 = ADC module is in 1st precharge stage
000 = ADC module is not converting

Note 1: If ADOSC=1, and FOSC<FRC, these bits may be invalid.

26.11 Register Definitions: Modulation Control

REGISTER 26-1: MDCON0: MODULATION CONTROL REGISTER

R/W-0/0	U-0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	R/W-0/0
MDEN	—	MDOUT	MDOPOL	—	—	—	MDBIT(2)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **MDEN:** Modulator Module Enable bit
1 = Modulator module is enabled and mixing input signals
0 = Modulator module is disabled and has no output

bit 6 **Unimplemented:** Read as ‘0’

bit 5 **MDOUT:** Modulator Output bit
Displays the current output value of the modulator module.(1)

bit 4 **MDOPOL:** Modulator Output Polarity Select bit
1 = Modulator output signal is inverted; idle high output
0 = Modulator output signal is not inverted; idle low output

bit 3-1 **Unimplemented:** Read as ‘0’

bit 0 **MDBIT:** Allows software to manually set modulation source input to module(2)

Note 1: The modulated output frequency can be greater and asynchronous from the clock that updates this register bit, the bit value may not be valid for higher speed modulator or carrier signals.

2: MDBIT must be selected as the modulation source in the MDSRC register for this operation.

31.5.2 SLAVE RECEPTION

When the R/$\overline{W}$ bit of a matching received address byte is clear, the R/$\overline{W}$ bit of the SSPxSTAT register is cleared. The received address is loaded into the SSPxBUF register and acknowledged.

When the overflow condition exists for a received address, then not Acknowledge is given. An overflow condition is defined as either bit BF of the SSPxSTAT register is set, or bit SSPOV of the SSPxCON1 register is set. The BOEN bit of the SSPxCON3 register modifies this operation. For more information see Register 31-4.

An MSSP interrupt is generated for each transferred data byte. Flag bit, SSPxIF, must be cleared by software.

When the SEN bit of the SSPxCON2 register is set, SCL will be held low (clock stretch) following each received byte. The clock must be released by setting the CKP bit of the SSPxCON1 register, except sometimes in 10-bit mode. See **Section 31.5.6.2 "10-bit Addressing Mode"** for more detail.

31.5.2.1 7-bit Addressing Reception

This section describes a standard sequence of events for the MSSP module configured as an I^2C slave in 7-bit Addressing mode. Figure 31-14 and Figure 31-15 is used as a visual reference for this description.

This is a step by step process of what typically must be done to accomplish I^2C communication.

1. Start bit detected.
2. S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
3. Matching address with R/$\overline{W}$ bit clear is received.
4. The slave pulls SDA low sending an $\overline{ACK}$ to the master, and sets SSPxIF bit.
5. Software clears the SSPxIF bit.
6. Software reads received address from SSPxBUF clearing the BF flag.
7. If SEN = 1; Slave software sets CKP bit to release the SCL line.
8. The master clocks out a data byte.
9. Slave drives SDA low sending an $\overline{ACK}$ to the master, and sets SSPxIF bit.
10. Software clears SSPxIF.
11. Software reads the received byte from SSPxBUF clearing BF.
12. Steps 8-12 are repeated for all received bytes from the master.
13. Master sends Stop condition, setting P bit of SSPxSTAT, and the bus goes idle.

31.5.2.2 7-bit Reception with AHEN and DHEN

Slave device reception with AHEN and DHEN set operate the same as without these options with extra interrupts and clock stretching added after the eighth falling edge of SCL. These additional interrupts allow the slave software to decide whether it wants to $\overline{ACK}$ the receive address or data byte, rather than the hardware. This functionality adds support for PMBus™ that was not present on previous versions of this module.

This list describes the steps that need to be taken by slave software to use these options for I^2C communication. Figure 31-16 displays a module using both address and data holding. Figure 31-17 includes the operation with the SEN bit of the SSPxCON2 register set.

1. S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
2. Matching address with R/$\overline{W}$ bit clear is clocked in. SSPxIF is set and CKP cleared after the eighth falling edge of SCL.
3. Slave clears the SSPxIF.
4. Slave can look at the ACKTIM bit of the SSPxCON3 register to determine if the SSPxIF was after or before the $\overline{ACK}$.
5. Slave reads the address value from SSPxBUF, clearing the BF flag.
6. Slave sets $\overline{ACK}$ value clocked out to the master by setting ACKDT.
7. Slave releases the clock by setting CKP.
8. SSPxIF is set after an $\overline{ACK}$, not after a NACK.
9. If SEN = 1 the slave hardware will stretch the clock after the $\overline{ACK}$.
10. Slave clears SSPxIF.

Note: SSPxIF is still set after the ninth falling edge of SCL even if there is no clock stretching and BF has been cleared. Only if NACK is sent to master is SSPxIF not set

11. SSPxIF set and CKP cleared after eighth falling edge of SCL for a received data byte.
12. Slave looks at ACKTIM bit of SSPxCON3 to determine the source of the interrupt.
13. Slave reads the received data from SSPxBUF clearing BF.
14. Steps 7-14 are the same for each received data byte.
15. Communication is ended by either the slave sending an $\overline{ACK}$ = 1, or the master sending a Stop condition. If a Stop is sent and Interrupt on Stop Detect is disabled, the slave will only know by polling the P bit of the SSPxSTAT register.

FIGURE 31-19: I²C SLAVE, 7-BIT ADDRESS, TRANSMISSION (AHEN = 1)

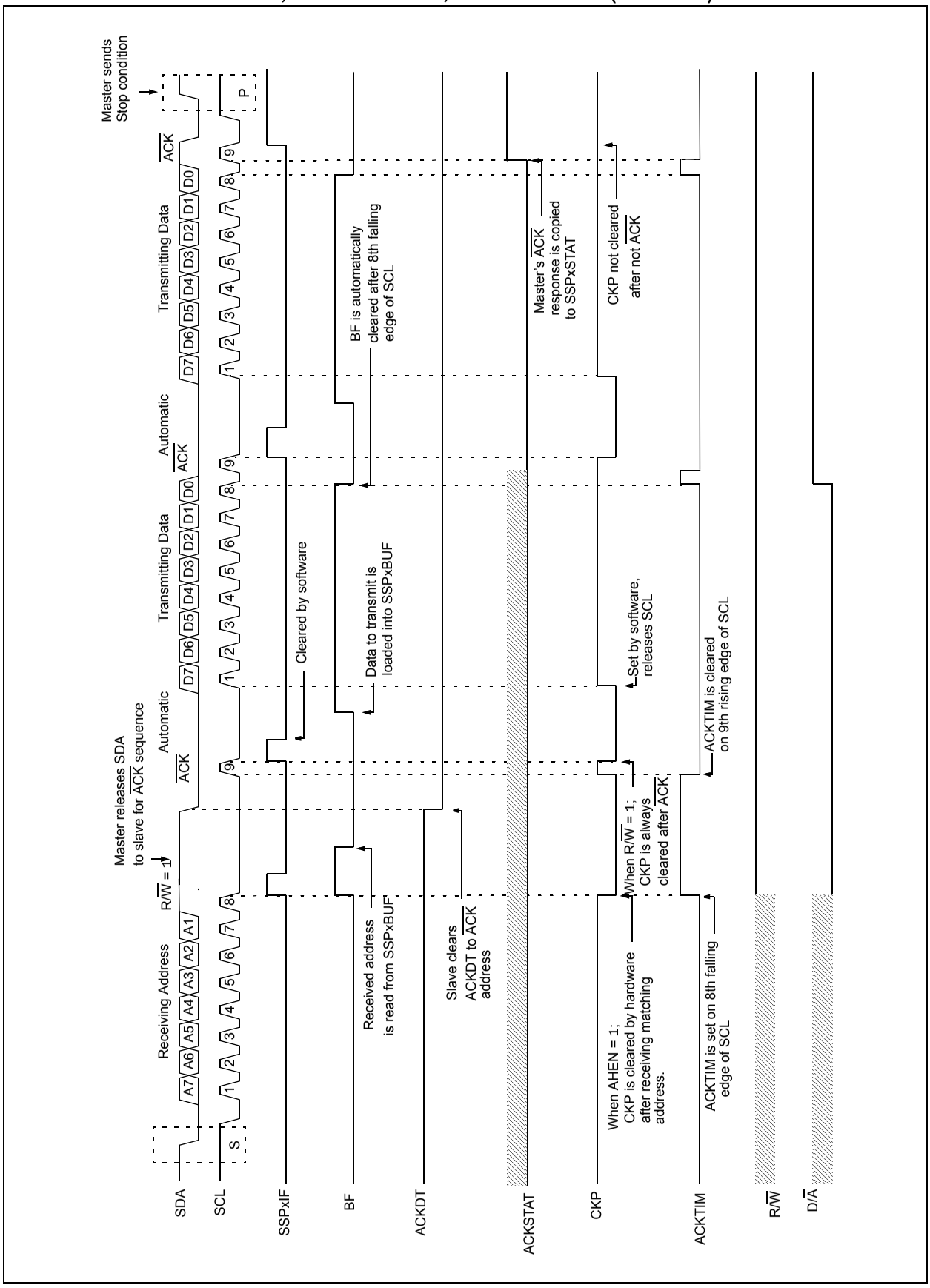


FIGURE 34-1: CLOCK REFERENCE BLOCK DIAGRAM

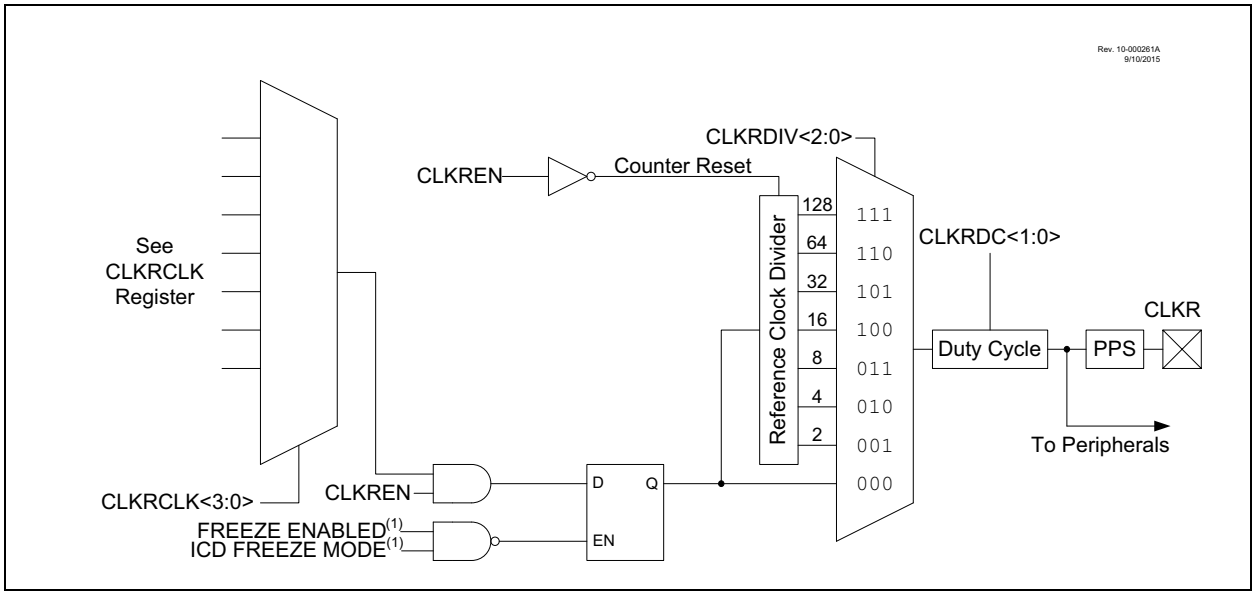
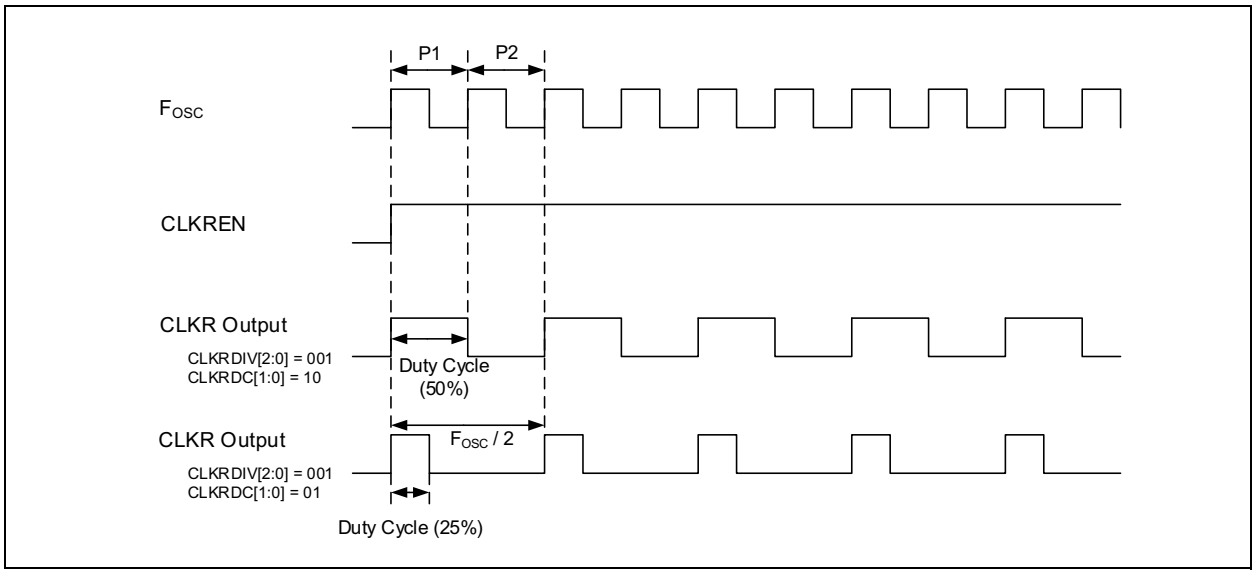


FIGURE 34-2: CLOCK REFERENCE TIMING



36.2 Instruction Descriptions

ADDFSR — Add Literal to FSRn

Syntax:	[*label*] ADDFSR FSRn, k
Operands:	-32 ≤ k ≤ 31 n ∈ [0, 1]
Operation:	FSR(n) + k → FSR(n)
Status Affected:	None
Description:	The signed 6-bit literal 'k' is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h-FFFFh. Moving beyond these bounds will cause the FSR to wrap-around.

ADDLW — Add literal and W

Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal 'k' and the result is placed in the W register.

ADDWF — Add W and f

Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ADDWFC — ADD W and CARRY bit to f

Syntax:	[*label*] ADDWFC f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) + (C) → dest
Status Affected:	C, DC, Z
Description:	Add W, the Carry flag and data memory location 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location 'f'.

ANDLW — AND literal with W

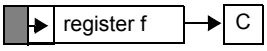
Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W register.

ANDWF — AND W with f

Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ASRF — Arithmetic Right Shift

Syntax:	[*label*] ASRF f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f<7>)→ dest<7> (f<7:1>) → dest<6:0>, (f<0>) → C,
Status Affected:	C, Z
Description:	The contents of register 'f' are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

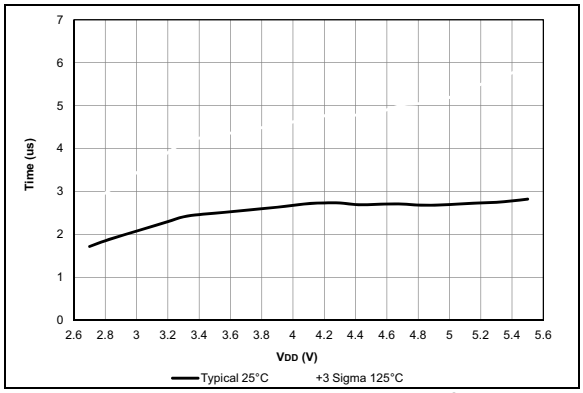


FIGURE 38-67: *BOR Response Time, PIC16F18856/76 Only.*

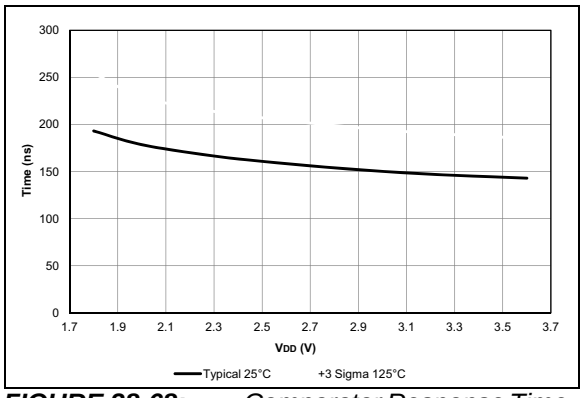


FIGURE 38-68: *Comparator Response Time, Falling Edge, PIC16LF18856/76 Only.*

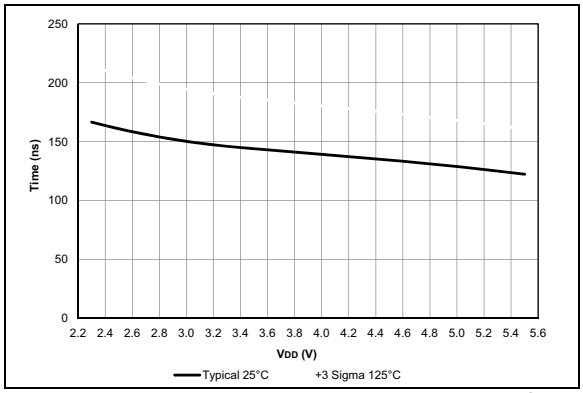


FIGURE 38-69: *Comparator Response Time, Falling Edge, PIC16F18856/76 Only.*

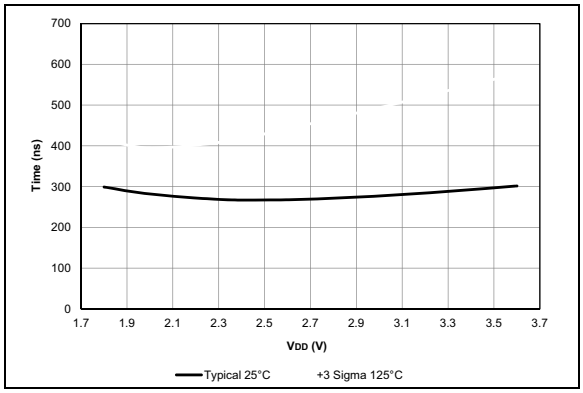


FIGURE 38-70: *Comparator Response Time, Rising Edge, PIC16LF18856/76 Only.*

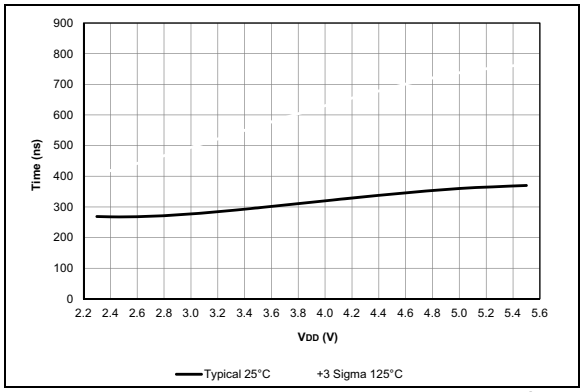


FIGURE 38-71: *Comparator Response Time, Rising Edge, PIC16F18856/76 Only.*

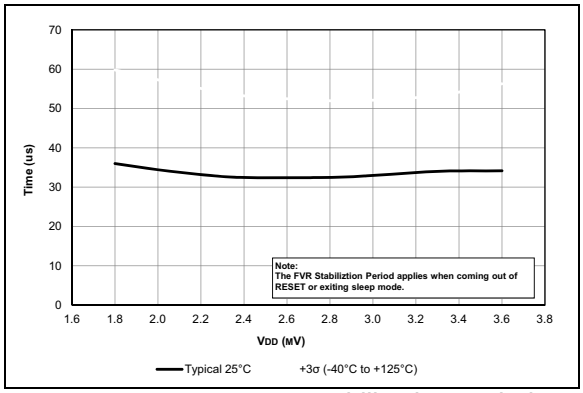
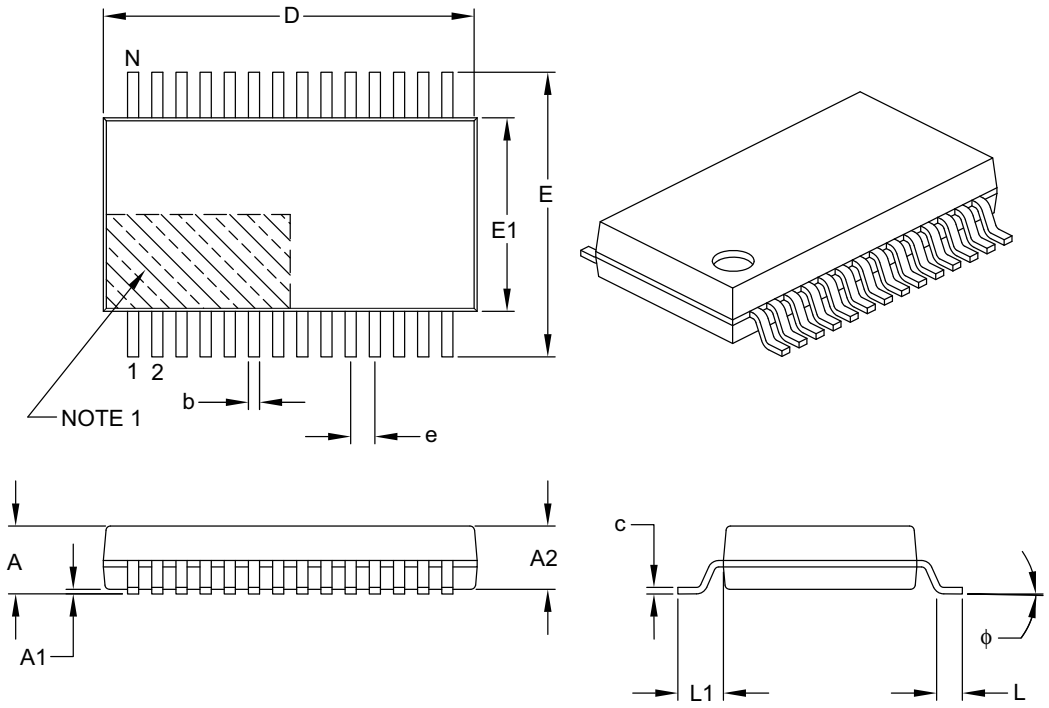


FIGURE 38-72: *FVR Stabilization Period, PIC16LF18856/76 Only.*

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

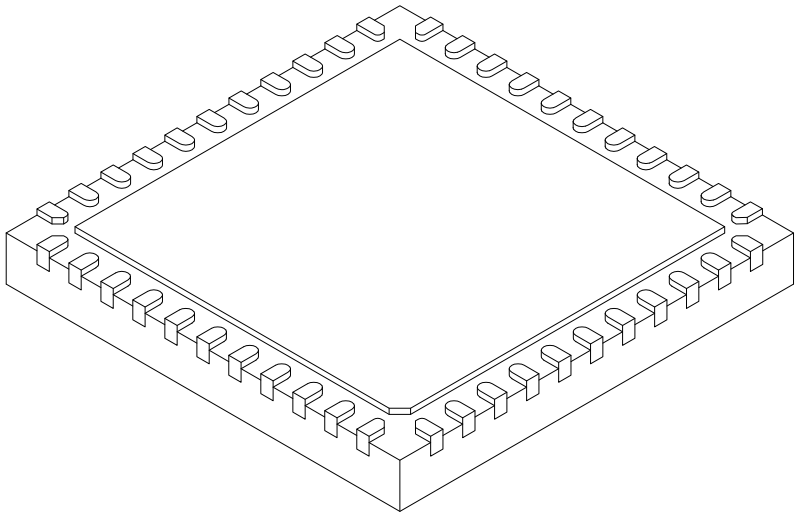
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

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